

REMARKS

Claims 1-3 are now pending in the application. Claims 1 and 3 are now amended. Claims 4-6 are now cancelled. The claim amendments are fully supported by the application as filed and do not introduce new subject matter. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

RESTRICTION/ELECTION REQUIREMENT

Applicant thanks the Examiner for acknowledging Applicant's provisional election of the species of Figures 1-9, with traverse. Applicant further thanks the Examiner for pointing out that the election is of Claims 1-6, not Claims 1-18 as previously identified.

TITLE/SPECIFICATION

The Office Action objects to the title as not being clearly indicative of the invention to which the claims are directed.

Applicant now amends the title to recite, "Lead Frame For Accommodating Semiconductor Chips Of Various Different Sizes."

Applicant submits that the amended title clearly identifies the invention to which the claims are directed.

REJECTION UNDER 35 U.S.C. § 112

Claims 1-6 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point and distinctly claim the subject matter which Applicant regards as the invention. This rejection is respectfully traversed.

Claims 4-6 are now cancelled. Therefore, this Section 112 rejection is now moot with respect to Claims 4-6.

Claims 1 and 3 recite, in part and with reference to Figures 1 – 9 for exemplary purposes only as the invention includes numerous embodiments, a lead frame for packaging a semiconductor chip comprising: a frame-shaped land 2; a die pad 11; a semiconductor chip 21, 31, 41 mounted to the die pad 11; first to fourth support portions 7, 8, 9, and 10 formed in four corners of the land and supporting the die pad so that the die pad is located inside the land; and first to fourth groups of lead members 3, 4, 5, and 6 having first ends and second ends that are opposite to the first ends, the first ends being fixed to the land 2 and the second ends being parallel in each group. The second ends of the lead members are connected to the semiconductor chip with wires 26, 46, 36. The lead frame can accommodate semiconductor chips of various different sizes (Figures 4, 6, and 8).

As set forth above, the features of independent Claims 1 and 3, and those claims dependent therefrom, are illustrated in the figures as filed and the claims comply with Section 112. Therefore, Applicant respectfully requests reconsideration and withdrawal of this Section 112 rejection.

REJECTION UNDER 35 U.S.C. § 102

Claims 1-6 stand rejected under 35 U.S.C. § 102(e) as being anticipated by Miyaki et al. (U.S. Pat. No. 6,340,837). This rejection is respectfully traversed.

Claims 4-6 are now cancelled. Therefore, the rejection is moot with respect to these claims.

The relevant features of amended independent Claims 1 and 3 are set forth above.

The Miyaki et al. reference appears to disclose, with reference to Figures 1 and 2, leads 2 having a first end distal to a semiconductor chip 10 and a second end proximate to the semiconductor chip 10 and connected to the semiconductor chip with wires 12. The Miyaki et al. reference fails to disclose or suggest that the second ends connected to the semiconductor chip 10 with the wires are parallel to each other. Further, the Miyaki et al. reference fails to disclose or suggest that its device can accommodate semiconductor chips of different sizes.

The Miyaki et al. reference fails to disclose or suggest first to fourth groups of lead members having first ends and second ends that are opposite to the first ends, the first ends being fixed to the land, and the second ends being parallel in each group and connected to the semiconductor chip with a wire, as set forth in amended Claims 1 and 3. Further, the Miyaki et al. reference fails to disclose or suggest a device that can accommodate semiconductor chips of various different sizes, as set forth in amended Claims 1 and 3.

As set forth above, the Miyaki et al. reference fails to disclose or suggest each and every feature of amended Claims 1 and 3. Therefore, the Miyaki et al. reference

fails to anticipate or render obvious amended Claims 1 and 3 and those claims dependent therefrom.

Applicant respectfully requests reconsideration and withdrawal of this Section 102 rejection.

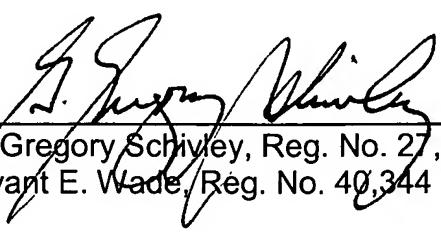
CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action and the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

Dated: Dec 19, 2005

By:


G. Gregory Schivley, Reg. No. 27,382
Bryant E. Wade, Reg. No. 40,344

Harness, Dickey & Pierce, P.L.C.
P.O. Box 828
Bloomfield Hills, Michigan 48303
(248) 641-1600
GGS/BGS/les